

FEATURES AND SPECIFICATIONS

Features and Benefits

- Sizes 16 to 64 circuits
- DIN 41612 and IEC 603-2 compatible
- Two points of contact provide low insertion force and reliable connection

Reference Information

Product Specification: PS-53230/PS-53316
 Packaging: Tray
 UL File No.: E29179 (for 53230 only)
 CSA File No.: LR19980
 Mates With: 52299 and 52479
 Designed In: Millimeters

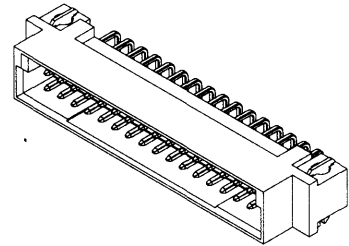
Electrical

Voltage: 300V
 Current: 2.0A
 Contact Resistance: 20mΩ max.
 Dielectric Withstanding Voltage: 1000V AC
 Insulation Resistance: 10⁶ MΩ min.

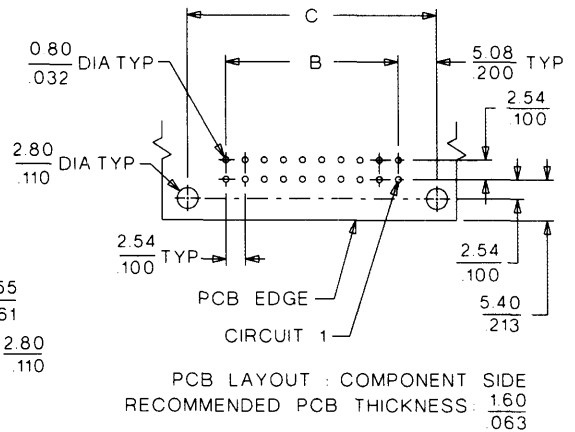
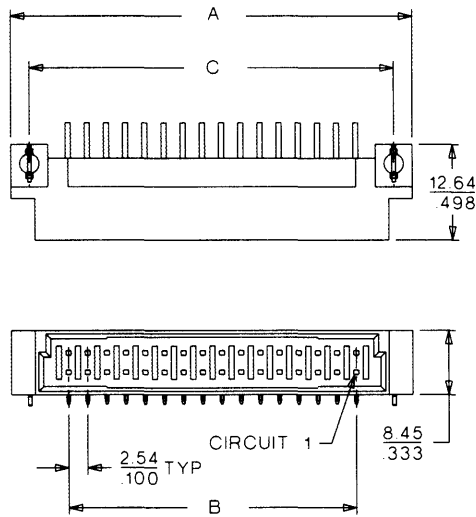
Physical

Housing: Glass-filled PBT, UL 94V-0
 Contact: Brass
 Metal Peg: Phosphor Bronze
 Plating: See Table
 Operating Temperature: -55 to +105°C

molex® 2.54mm (.100") Pitch DIN 41612 Header 53230/53316 Right Angle



CATALOG DRAWING (FOR REFERENCE ONLY)



ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.		Dimension		
	Without Metal Peg	With Metal Peg	A	B	C
16	53230-016X	53316-016X	32.84 (1.293)	17.78 (.700)	27.94 (1.100)
20	53230-020X	53316-020X	37.92 (1.493)	22.86 (.900)	33.02 (1.300)
32	53230-032X	53316-032X	53.16 (2.093)	38.10 (1.500)	48.26 (1.900)
44	53230-044X	53316-044X	68.40 (2.693)	53.34 (2.100)	63.50 (2.500)
50	53230-050X	53316-050X	76.02 (2.993)	60.96 (2.400)	71.12 (2.800)
64	53230-064X	53316-064X	93.80 (3.693)	78.74 (3.100)	88.90 (3.500)

Replace X with plating no., 0-3

Plating No. 0: 0.1µm Gold with Nickel underplate overall and Tin/Lead in solder area
 Plating No. 1: 0.3µm Gold with Nickel underplate overall and Tin/Lead in solder area
 Plating No. 2: 0.5µm Gold with Nickel underplate overall and Tin/Lead in solder area
 Plating No. 3: 0.7µm Gold with Nickel underplate overall and Tin/Lead in solder area